

SMB Plastic-Encapsulate Diodes

General Purpose Rectifier Diodes

Features:

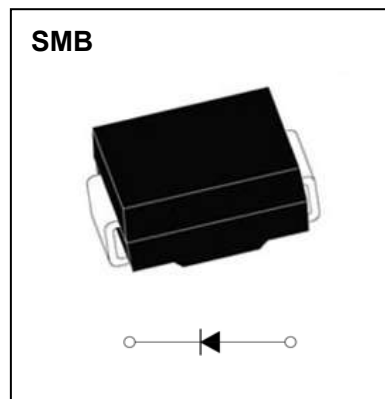
- $I_{F(AV)}$ 2A
- V_{RRM} 50V-1000V
- High surge current capability
- Polarity: Color band denotes cathode

Applications:

- Rectifier

Marking

- S2X
- X : From A To M



Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	S2						
				A	B	D	G	J	K	M
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V		35	70	140	280	420	560	700
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, $T_L=100\text{ C}$	2.0						
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, $T_a=25\text{ C}$	60						
Operation Junction and Storage Temperature Range	T_J, T_{STG}	$^{\circ}\text{C}$		-55 ~ +150						

Electrical Characteristics (T=25 $^{\circ}\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	S2					
				A	B	D	G	J	K
Peak Forward Voltage	V_F	V	$I_F=2.0\text{A}$	1.0					
Peak Reverse Current	I_{RRM1}	μA	$V_{RM}=V_{RRM}$	$T_a=25^{\circ}\text{C}$					
	I_{RRM2}			$T_a=125^{\circ}\text{C}$					
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^{\circ}\text{C}/\text{W}$	Between junction and ambient	53					
	$R_{\theta J-L}$		Between junction and terminal	16					

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.27" x 0.27" (7.0 mm x 7.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

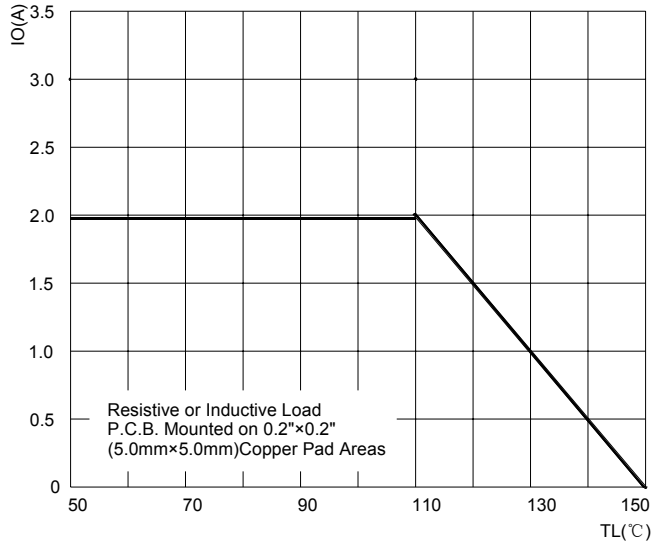


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

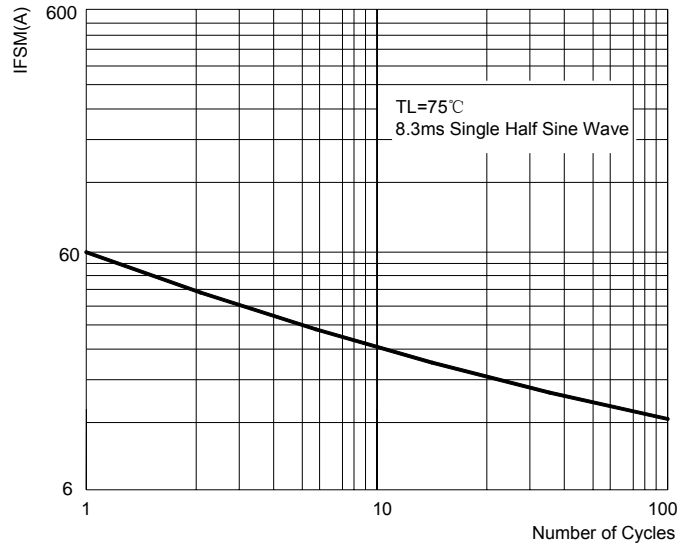


FIG.3: TYPICAL FORWARD CHARACTERISTICS

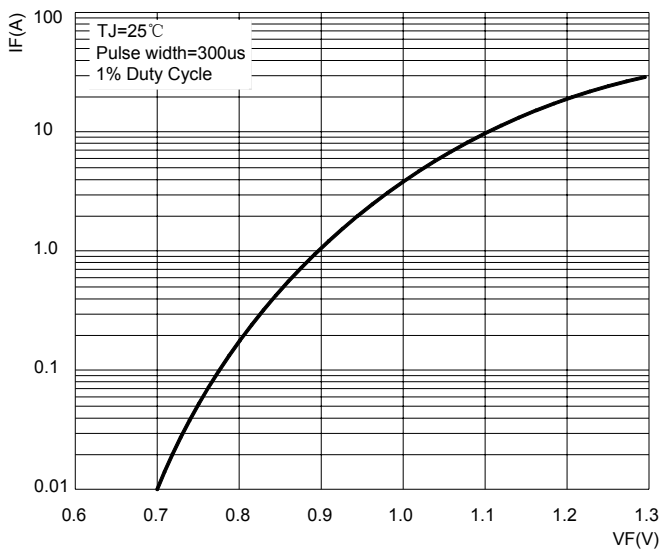
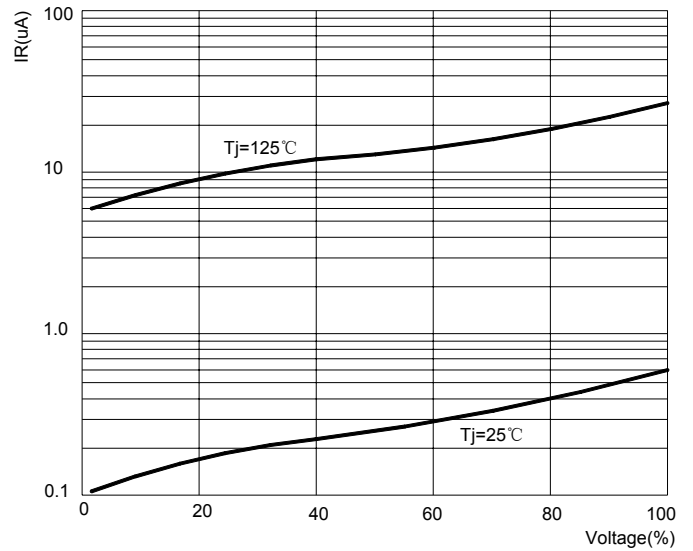
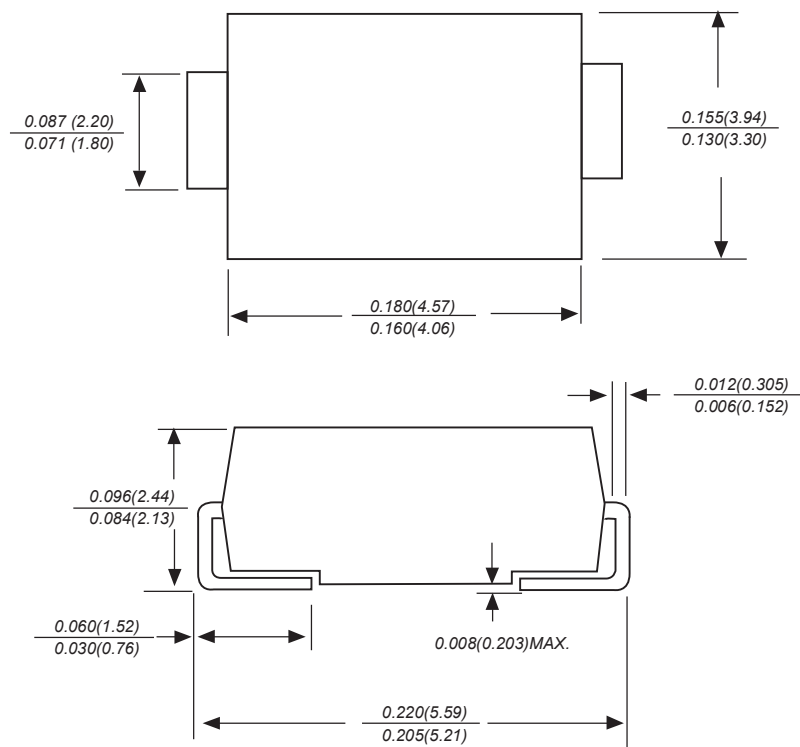


FIG.4: TYPICAL REVERSE CHARACTERISTICS

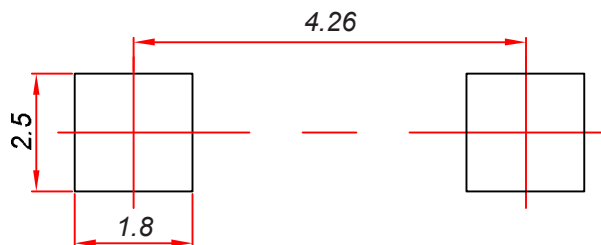


SMB Package Outline Dimensions



Dimensions in inches and (millimeters)

SMB Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05 \text{ mm.}$
3. The pad layout is for reference purposes only.

Reel Taping Specifications For Surface Mount Devices-SMB

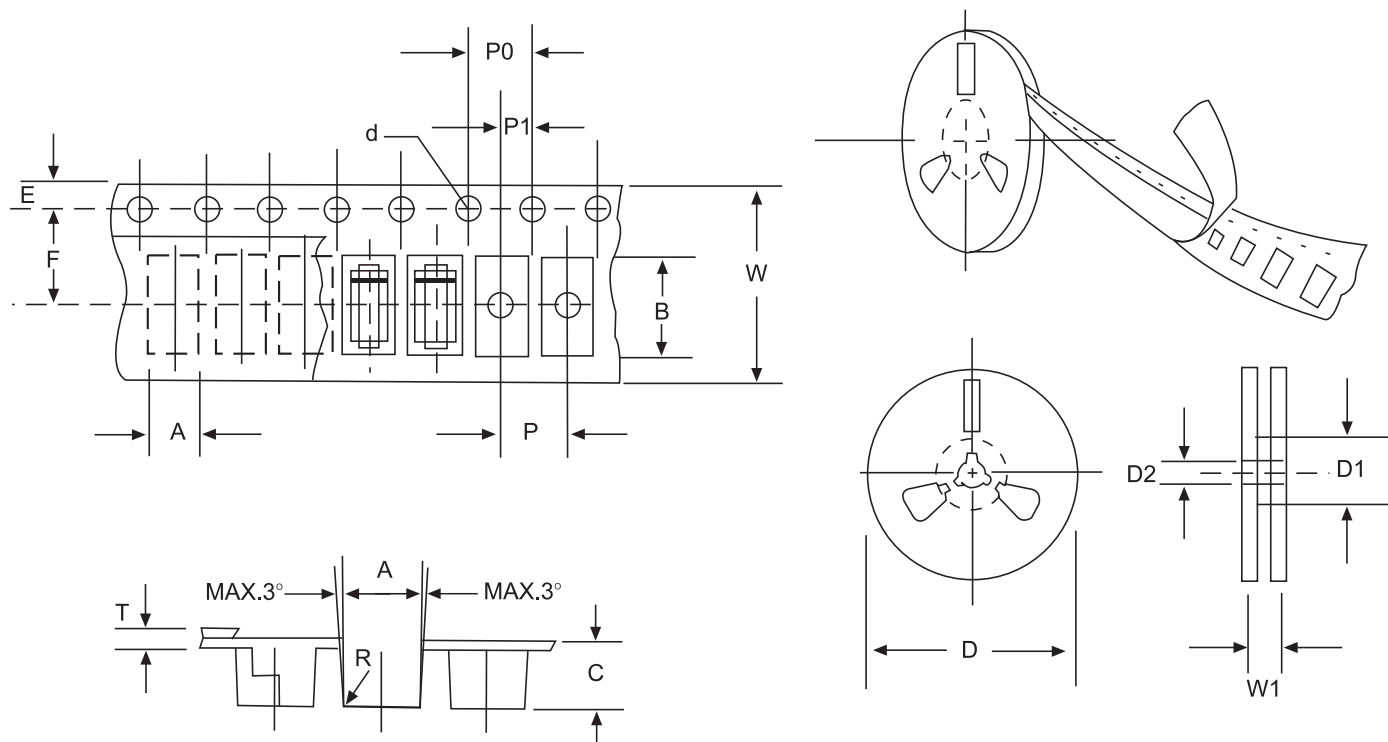


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMBG mm(inch)
Carrier width	A	4.09±0.1(0.161±0.004)
Carrier length	B	5.82±0.1(0.229±0.004)
Carrier depth	C	2.50±0.1(0.100±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75 ±0.1(0.069±0.004)
Punch hole position	F	5.65±0.05(0.222±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.32±0.1(0.013±0.004)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.